



Product/Process Change Notice - PCN 17_0003 Rev. A

Analog Devices, Inc. Three Technology Way Norwood, Massachusetts 02062-9106

This notice is to inform you of a change that will be made to certain ADI products (see Appendix A) that you may have purchased in the last 2 years. **Any inquiries or requests with this PCN (additional data or samples) must be sent to ADI within 30 days of publication date.** ADI contact information is listed below.

Note: Revised fields are indicated by a red field name. See Appendix B for revision history.

PCN Title: ADuM1280W/ADuM1281W/ADuM1285W/ADuM1286W Die Revision, Data Sheet Change, Test Platform Migration, and Assembly Site Transfer

Publication Date: 24-Jul-2018

Effectivity Date: 24-Jul-2018 *(the earliest date that a customer could expect to receive changed material)*

Revision Description:

Correction to attachment 3 (Test Correlation Report) title.

Correction to attachment 4 (Assembly Material Set Comparison) mold compound used on the original ADuM128xW in Carsem from Sumitomo 6600H to Sumitomo G600C.

This PCN revision only impacts the documentation of the original material, not the revised material, so distribution to the customers is optional.

The purpose for this PCN revision is to ensure the PPAP information being generated and the PCN information match.

Description Of Change:

Die Revision:

- 1) Additional layer of polyimide passivation over non-coil die.
- 2) Increased look-ahead delay in coil driver circuitry.

Data Sheet Change:

- 1) Increased maximum propagation delay specification on C grade models(ADuM128xWCRZ). Specific changes outlined in attachment below.
- 2) Increased minimum operating voltage from 3.0V to 3.135V. Changed 3.3V Power Supply tolerance from +10%/-10% to +10%/-5%.

Test Platform Migration:

- 1) The high voltage test platform used to verify the insulation performance of the ADuM1280W/ADuM1281W/ADuM1285W/ADuM1286W products during production will be migrated from the Harris-Tuvey 9464 to the Mess-& Prüfsysteme GmbH (MPS) PD test system.

Assembly Site Transfer:

- 1) ADI has qualified and will be utilizing assembly subcontractor ASE Chungli, Taiwan for 8L SOIC_N Isolator products. ADI has qualified ASE Chungli's standard bill of materials in the SOIC_N package. See Bill of Materials change description attached below.

Reason For Change:

Die Revision:

- 1) Polyimide offers the following advantages: improved ESD robustness, enhanced protection against die scratches, package stresses, surface ESD/EOS events and radiation.
- 2) Increase manufacturability to ensure continuity of supply.

Data Sheet Change:

- 1) Increase in look-ahead delay increased overall propagation delay through signal path.
- 2) Increase manufacturability to ensure continuity of supply.

Test Platform Migration:

- 1) To maintain future continuity of supply and gain the ability to datalog high voltage production test measurements. ADI is currently relying on an aging high voltage test platform (Harris-Tuvey 9464) for the ADuM128xW products.

Assembly Site Transfer:

- 1) To align with ADI's isolator manufacturing strategy. The use of ADI qualified ASE Chungli as an assembly site for this package will ensure continued source of product supply. ADI's assembly subcontractors manufacture our products using Analog Devices specified manufacturing flows, process controls and monitors. This assures that our customers receive the same level of quality and reliability on products they receive from qualified ADI manufacturing locations.

Impact of the change (positive or negative) on fit, form, function & reliability:

No change to fit, form, or reliability.

Summary of Supporting Information:

Qualification has been performed per AEC-Q100, Stress Test Qualification for Integrated Circuits. See attached Qualification Results Summary. Test correlation and validation has been performed, see attached Test Correlation report. Data Sheet changes will be reflected in Rev D. See attached data sheet specification comparison for propagation delay revision details.

Supporting Documents

Attachment 1: Type: Datasheet Specification Comparison

ADI_PCN_17_0003_Rev_A_ADuM128xW_Propagation_Delay_Comparison.pdf

Attachment 2: Type: Qualification Results Summary

ADI_PCN_17_0003_Rev_A_ADuM128xW_Qualification_Results_Summary.pdf

Attachment 3: Type: Test Correlation Report

ADI_PCN_17_0003_Rev_A_ADuM128xW_Test_Correlation_Report_B.pdf

Attachment 4: Type: Detailed Change Description

ADI_PCN_17_0003_Rev_A_ADuM128xW_SOIC_N_Material_Set_Comparison.pdf

For questions on this PCN, please send an email to the regional contacts below or contact your local ADI sales representatives.

Americas:
PCN_Americas@analog.com

Europe:
PCN_Europe@analog.com

Japan:
PCN_Japan@analog.com

Rest of Asia:
PCN_ROA@analog.com

Appendix A - Affected ADI Models**Existing Parts - Product Family / Model Number (24)**

ADUM1280 / ADUM1280WARZ	ADUM1280 / ADUM1280WARZ-RL7	ADUM1280 / ADUM1280WBRZ	ADUM1280 / ADUM1280WBRZ-RL7	ADUM1280 / ADUM1280WCRZ
ADUM1280 / ADUM1280WCRZ-RL7	ADUM1281 / ADUM1281WARZ	ADUM1281 / ADUM1281WARZ-RL7	ADUM1281 / ADUM1281WBRZ	ADUM1281 / ADUM1281WBRZ-RL7
ADUM1281 / ADUM1281WCRZ	ADUM1281 / ADUM1281WCRZ-RL7	ADUM1285 / ADUM1285WARZ	ADUM1285 / ADUM1285WARZ-RL7	ADUM1285 / ADUM1285WBRZ
ADUM1285 / ADUM1285WBRZ-RL7	ADUM1285 / ADUM1285WCRZ	ADUM1285 / ADUM1285WCRZ-RL7	ADUM1286 / ADUM1286WARZ	ADUM1286 / ADUM1286WARZ-RL7
ADUM1286 / ADUM1286WBRZ	ADUM1286 / ADUM1286WBRZ-RL7	ADUM1286 / ADUM1286WCRZ	ADUM1286 / ADUM1286WCRZ-RL7	

Appendix B - Revision History

Rev	Publish Date	Effectivity Date	Rev Description
Rev. -	31-Jan-2017	01-May-2017	Initial Release
Rev. A	24-Jul-2018	24-Jul-2018	Correction to attachment 3 (Test Correlation Report) title. Correction to attachment 4 (Assembly Material Set Comparison) mold compound used on the original ADuM128xW in Carsem from Sumitomo 6600H to Sumitomo G600C. This PCN revision only impacts the documentation of the original material, not the revised material, so distribution to the customers is optional. The purpose for this PCN revision is to ensure the PPAP information being generated and the PCN information match.

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